

Specification for Approval

| Customer: | |
|------------------|--|
| | |

Model Name:

| Si | Customer approval | | |
|--------------|-------------------|-------------|--|
| R&D Designed | R&D Approved | QC Approved | |
| Peter | Peng Jun | | |



Revision Record

| REV NO. | REV DATE | CONTENTS | Note |
|---------|------------|-----------|------|
| A | 2022-01-17 | NEW ISSUE | |
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1. Scope

This specification defines general provisions as well as inspection standards for TFT module supplied by AMSON electronics.

If the event of unforeseen problem or unspecified items may occur, naturally shall negotiate and agree to solution.

2. General Information

| ITEM | STANDARD VALUES | UNITS |
|--------------------------------|-------------------------------------|-------|
| LCD type | 3.5"TFT | - |
| Dot arrangement | 240(RGB)×320 | dots |
| Color filter array | RGB vertical stripe | - |
| Display mode | TN / Transflective / Normally White | - |
| Gray Scale Inversion Direction | 12 O'clock | |
| Eyes Viewing Direction | 6 O'clock | |
| Driver IC | ILI9341V | - |
| Module size | 64.00(W)×85.00(H)×4.2(T) | mm |
| Active area | 53.64(W)×71.52(H) | mm |
| Dot pitch | 0.2235(W)×0.2235(H) | mm |
| Interface | SPI + 18-bit RGB interface | - |
| Operating temperature | -20 ~ +70 | °C |
| Storage temperature | -30 ~ +80 | °C |
| Back Light | 6 White LED In Serial | - |



3. External Dimensions



YU DU AMSON ELECTRONICS CO.,LTD.



4. Interface Description

| Т | FΤ | |
|---|----|--|
| | | |

| PIN NO. | PIN NAME | DESCRIPTION | | | |
|---------|----------|---|--|--|--|
| 1 | LEDA | LED backlight anode. | | | |
| 2 | VSS | Power ground. | | | |
| 3 | LEDK | LED backlight cathode. | | | |
| 4 | VSS | ower ground. | | | |
| 5 | VDD | Power Supply Voltage | | | |
| 6~8 | VSS | Power ground. | | | |
| 9 | VSYNC | Frame synchronizing signal for RGB interface operation. | | | |
| 10 | VSS | Power ground. | | | |
| 11 | RESET | Reset signal input terminal, active at 'L'. | | | |
| 12~14 | VSS | Power ground. | | | |
| 15 | /CS | Chip select input (Low enable). | | | |
| 16 | VSS | Power ground. | | | |
| 17 | SDO | Serial data output | | | |
| 18 | SDA | Serial data input | | | |
| 19 | VSS | Power ground. | | | |
| 20 | SCL | Synchronizing clock signal in SPI mode. | | | |
| 21 | VSS | Power ground. | | | |
| 22~27 | B5~B0 | 3lue data input. | | | |
| 28 | DE | Data DE signal for RGB interface operation. | | | |
| 29 | VSS | Power ground. | | | |
| 30 | HSYNC | Line synchronizing signal for RGB interface operation. | | | |
| 31 | VSS | Power ground. | | | |
| 32 | DCLK | Dot clock signal for RGB interface operation. | | | |
| 33 | VSS | Power ground. | | | |
| 34~39 | G5~G0 | Green data input. | | | |
| 40 | VSS | Power ground. | | | |
| 41~46 | R5~R0 | Red data input. | | | |
| 47~50 | VSS | Power ground. | | | |

RTP

| PIN NO. | PIN NAME |
|---------|----------|
| 1 | YU |
| 2 | XR |
| 3 | YD |
| 4 | XL |



5. Absolute Maximum Ratings

| Item | Symbol | Min. | Max. | Unit |
|-----------------------|--------|------|---------|------|
| Power Supply Voltage | VDD | -0.3 | 4.5 | V |
| Input Voltage | Vin | 0 | VDD+0.3 | V |
| Operating Temperature | Тор | -20 | 70 | °C |
| Storage Temperature | Tst | -30 | 80 | °C |
| Storage Humidity | HD | - | 90 | %RH |

6. DC Characteristics

| ltem | Symbol | Min. | Тур. | Max. | Unit | Remark |
|----------------------|-----------------|--------|------|--------|------|---------------------|
| Power Supply Voltage | VDD | 3.0 | 3.3 | 3.6 | V | - |
| Input High Voltage | VIH | 0.7VDD | - | VDD | V | Digital input pins |
| Input Low Voltage | V _{IL} | VSS | - | 0.3VDD | V | Digital input pins |
| Output High Voltage | V _{OH} | 0.8VDD | - | VDD | V | Digital output pins |
| Output Low Voltage | V _{OL} | VSS | - | 0.2VDD | V | Digital output pins |
| I/O Leak Current | ILI | -1 | - | 1 | uA | - |



7. Timing Characteristics

7.1 3-wires SPI Timing Characteristics



| Signal | Symbol | Parameter | min | max | Unit | Description |
|-----------|--------|-----------------------------|-----|-----|------|-------------|
| | tscycw | Serial Clock Cycle (Write) | 100 | - | ns | |
| | tshw | SCL "H" Pulse Width (Write) | 40 | - | ns | |
| 801 | tslw | SCL "L" Pulse Width (Write) | 40 | - | ns | |
| SUL | tscycr | Serial Clock Cycle (Read) | 150 | - | ns | |
| | tshr | SCL "H" Pulse Width (Read) | 60 | - | ns | |
| | tslr | SCL "L" Pulse Width (Read) | 60 | - | ns | |
| SDA / SDI | tsds | Data setup time (Write) | 30 | - | ns | |
| (Input) | tsdh | Data hold time (Write) | 30 | - | ns | |
| SDA / SDO | tacc | Access time (Read) | 10 | - | ns | |
| (Output) | toh | Output disable time (Read) | 10 | 50 | ns | |
| | tscc | SCL-CSX | 20 | - | ns | |
| COV | tchw | CSX "H" Pulse Width | 40 | - | ns | |
| USX | tcss | CSX SCI Time | 60 | - | ns | |
| | tcsh | CON-OUL TIME | 65 | - | ns | |

Note: Ta = 25 °C, VDDI=1.65V to 3.3V, VCI=2.5V to 3.3V, AGND=VSS=0V





7.2 RGB Interface Timing Characteristics



Note 1: The DE signal is not needed when RGB interface SYNC mode is selected. Note 2: VSPL='0', HSPL='0', DPL='0' and EPL='0' of "Interface Mode Control (B0h)" command.

| Parameters | Symbols | Condition | Min. | Тур. | Max. | Units |
|----------------------------|---------|-----------|------|------|------|--------|
| Horizontal Synchronization | Hsync | | 2 | 10 | 16 | DOTCLK |
| Horizontal Back Porch | HBP | | 2 | 20 | 24 | DOTCLK |
| Horizontal Address | HAdr | | - | 240 | - | DOTCLK |
| Horizontal Front Porch | HFP | | 2 | 10 | 16 | DOTCLK |
| Vertical Synchronization | Vsync | | 1 | 2 | 4 | Line |
| Vertical Back Porch | VBP | | 1 | 2 | - | Line |
| Vertical Address | VAdr | | - | 320 | - | Line |
| Vertical Front Porch | VFP | | 3 | 4 | - | Line |

Typical values are setting example when used with panel resolution 240 x 320 (QVGA), clock frequency 6.35MHz and frame



8. Backlight Characteristics

BL Circuit Diagram:

LEDA - K K LEDK

| ltem | Symbol | MIN | TYP | MAX | UNIT | Test Condition |
|-------------------------------|--------|-------|-------|-------|-------------------|----------------|
| Supply Voltage | Vf | 16.8 | 19.2 | 20.4 | V | lf=20mA |
| Supply Current | lf | - | 20 | 30 | mA | - |
| Luminous Intensity for LCM | - | 80 | 100 | 140 | Cd/m ² | lf=20mA |
| Life Time | - | 30000 | 50000 | - | Hr | lf=20mA |
| Backlight Color | | | | White | | |



9. Optical Characteristics

| Item | Conditions | | Min. | Тур. | Max. | Unit | Note | |
|----------------|-----------------------------|---------|------|-------|-------|--------|-------------|--|
| | Horizontal | θL | - | 60 | - | | | |
| Viewing Angle | TIONZONIA | θR | - | 60 | - | degree | (1) (2) (6) | |
| (CR>10) | Vortical | θΤ | - | 55 | - | uegree | (1),(2),(0) | |
| | ventical | θΒ | - | 60 | - | | | |
| Contrast Ratio | Center | | 100 | 150 | - | - | (1),(3),(6) | |
| Response Time | Rising + Fal | ling | - | 35 | - | ms | (1),(4),(6) | |
| | Red x | | | 0.524 | | - | | |
| | Red y Green x Green y | | | 0.339 | | - | | |
| | | | | 0.347 | | - | | |
| CF Color | | | | 0.536 | | - | | |
| Chromaticity | Blue x | Blue x | | 0.164 | Тур. | - | (1), (6) | |
| | Blue y | Blue y | | 0.158 | +0.05 | - | | |
| | White x | White x | | 0.320 | | - | | |
| | White y | | | 0.350 | | - | | |
| Uniformity | Un | | 80 | - | - | % | (1),(6) | |

Note (1) Measurement Setup: The LCD module should be stabilized at given temp. 25°C for 15 minutes to avoid abrupt temperature change during measuring. In order to stabilize the luminance, the measurement should be executed after lighting backlight for 15 minutes in a windless room.





Note (2) Definition of Viewing Angle



Note (3) Definition Of Contrast Ratio (CR)

The contrast ratio can be calculated by the following expression Contrast Ratio (CR) = L63 / L0

L63: Luminance of gray level 63, L0: Luminance of gray level 0

Note (4) Definition of response time



- Note (5) Definition of Transmittance (Module is without signal input) Transmittance = Center Luminance of LCD / Center Luminance of Back Light x 100%
- Note (6) Definition of color chromaticity (CIE1931)

Color coordinates measured at the center point of LCD



10. Reliability Test Conditions and Methods 10.1 Standard Specification for Reliability of LCD Module

| No | Test Item | Condition | Remarks |
|----|--|---|--|
| 1 | High Temperature Operation | Ts = +70℃, 240 hours | IEC60068-21:2007 GB2423.2-2008 |
| 2 | Low Temperature Operation | Ta = -20℃, 240 hours | IEC60068-2-1:2007 GB/2423.1-2008 |
| 3 | High Temperature Storage | Ta = +80℃, 240 hours | IEC60068-21:2007 GB/2423.2-2008 |
| 4 | Low Temperature Storage | Ta = -30℃, 240 hours | IEC60068-21:2007 GB/2423.1-2008 |
| 5 | Storage at High Temperature and Humidity | Ta = +60℃, 90% RH max,240hours | IEC60068-2-78 :2001 GB/T2423.3—2006 |
| 6 | Thermal Shock (non- operation) | -30℃ 30 min~+80℃ 30 min, Change time:5min, 20 Cycle | Start with cold temperature, End with high temperature, IEC60068-214:1984, GB/2423.22-2002 |
| 7 | ESD | C=150pF,R=330Ω,5point/panel Air:±8Kv,5times; Contact:±4Kv,5times (Environment:15℃~35℃, 30%~60%.86Kpa~106Kpa) | IEC61000-42:2001 GB/T17626.2-2006 |
| 8 | Vibration Test | Frequency range:10~55Hz Stroke:1.5mm Sweep:10Hz~55Hz~1 0Hz 2 hours for each direction of X.Y.Z (6 hours for total) | IEC60068-2-6:1982 GB/T2423.101995 |
| 9 | Mechanical Shock (NonOp) | Half Sine Wave60G 6ms, ±X,±Y,±Z 3times for each direction | IEC60068-2-27:1987 GB/T2423.5—1995 |
| 10 | Package Drop Test | Height:80cm, 1corner,3 edges,6 surfaces | IEC60068-2-32:1990 GB/T2423.8—1995 |

Note1: Ts is the temperature of panel's surface. Note2: Ta is the ambient temperature of sample.



10.2 Testing Conditions and Inspection Criteria For the final test, the testing sample must be stored at room temperature for 24 hours. After the tests listed in Table 9.2, standard specifications for reliability will be executed in order to ensure stability.

| No. | Item | Test Model | In section Criteria |
|-----|------------------------|------------------------|--|
| 01 | Current Consumption | Refer To Specification | The current consumption should conform to the product specification. |
| 02 | Contrast | Refer To Specification | After the tests have been executed, the contrast must be larger than half of its initial value prior to the tests. |
| 03 | Appearance | Visual inspection | Defect free. |

10.3 MTBF

| | Functions, | performance, | appearance, | etc. | shall | be | free | from |
|------|--|--|--|--------------------------|-------------------------------|----------------------|------------------|------------------|
| MTBF | remarkable and storage (50±10% R | deterioration w e conditions roo H), and in area | ithin 50,000 hc om temperatur not exposed to | ours u e (25 direc | nder or ±5℃), t sun lig | dina norm ght. | ry ope nal hu | rating midity |
| MTBF | and storage (50±10% R | e conditions roo H), and in area | om temperatur not exposed to | e (25 direc | ±5℃), t sun liq | norm ght. | nal hu | midit |

11. Inspection Standard

This standard of Quality Assurance confirms to the quality of LCD module products supplied by Tecenstar.

11.1 Quality Test

Before delivering, the supplier should conduct the following tests to confirm the quality of products.

- Electrical-Optical Characteristics: According to the individual specification to test the product.
- Appearance Characteristics: According to the individual specification to test the product.
- Reliability Characteristics: According to the definition of reliability on the specification for testing products.

11.2 Delivery Test

Before delivering, the supplier should conduct the delivery test.

- Test method: According to MIL-STD105E.General Inspection Level II take a single Time.
- The defects classify of AQL as following:

Major defect: AQL = 0.65 Minor defect: AQL = 1.5 Total defects: AQL = 1.5

11.3 Non-conforming Analysis & Deal With Manners

- Purchaser should provide the data detail of non-conforming sample and the non-conforming.
- After receiving the data detail from purchaser, the analysis of non-conforming should be finished within two weeks.
- If the analysis can't be finished on time, supplier must notice purchaser 3 days in advance.

11.3.2 Disposition of non-conforming

- If any product defect be found during assembling, supplier must change the good for every defect after confirmation.
- Both supplier and customer should analyze the reason and discuss the disposition of non-conforming when the reason of nonconforming is not sure.

11.4 Agreement items

Both parties should negotiate together when the following problems happen.

- There is any problem of standard of quality assurance, and both sides should agree that it must be modified.
- There is any argument item which does not record in the standard of quality assurance.
- Any other special problem.

11.5 Standard of The Product Appearance Test

11.5.1 Manner of appearance test

- The test must be under 20W × 2 or 40W fluorescent light, and the distance of view must be at 30±5cm.
- When test the model of transmissive product must add the reflective plate.
- The test direction is base on around 10° of vertical line.
- Temperature: 25±5°C Humidity: 60±10%RH





Definition of area:



A:Viewing area B: Outside viewing area

11.5.2 Basic principle

- When the standard can not be described, AQL will be applied.
- The sample of the lowest acceptable quality level must be negotiated by both supplier and customer when any dispute happened.
- New item must be added on time when it is necessary.



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11.6 Inspection Specification

| NO. | ltem | | Crit | terion | | AQL |
|-----|--|---|---|---|---|------|
| 01 | Electrical Testing | 1.1 Missing vertical, horizontal segment, segment contrast defect. 1.2 Missing character, dot or icon. 1.3 Display malfunction. 1.4 No function or no display. 1.5 Current consumption exceeds product specifications. 1.6 LCD viewing angle defect. 1.7 Mixed product types. 1.8 Flicker | | | | 0.65 |
| 02 | Black or White spots or Bright spots or Color spots on LCD (Display only) | 2.1 White and black or color spots on display ≤ 0.25 mm, no more than Five spots. 2.2 Densely spaced: No more than three spots within 3mm. | | | | |
| | LCD and Touch Panel black spots. | 3.1 Round type: As followin $\Phi = (X+Y) / 2$ \downarrow | 0 0 0 | awing Size(mm) $\Phi \le 0.10$.10< $\Phi \le 0.20$.20< $\Phi \le 0.25$.25< $\Phi \le 0.30$ 0.30< Φ more than two | Acceptable Q'ty Accept no dense 1 1 0 0 0 spots within 3mm. | 1.5 |
| 03 | white spots, contamina tion (non – display) | 3.2 Line type: (As following → L ↓ W L ↓ ↓ L ← L ← * Densely space | drav gth m) 2.5 ed: N | ving) Width(mm) W≦0.02 W<0.08 0.08≦W | Acceptable Q'ty Accept no dense 1 Rejection | 1.5 |



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| NO. | ltem | Criterion | | | |
|-----|------------------|---|--|---|-----|
| | Polarizar | If bubbles are visible, judge using black spot specifications, not easy | Size Φ(mm) Φ≦0.30 | Acceptable Q'ty Accept no dense | |
| 04 | bubbles | to find, must check in | 0.30< Φ≤0.50 | 0 | 1.5 |
| | | specify direction | 0.50< Φ≦1.00 | 0 | |
| | | | 1.00< Φ | 0 | |
| | | | Total Q'ty | 0 | |
| 05 | Scratches | Follow NO.3 -2 Line Type. | | | |
| 06 | Chipped glass | Symbols:x: Chip lengthy: Chip widthk: Seal widtht: Glass thickL: Electrode pad length6.1 General glass chip:6.1.1 Chip on panel surface and cr $ientification (1,1) = 0$ <t< td=""><td>z: Chip thick ness a: LCD sid ack between pane in x: Chip len ing $x \leq 2MN$ /3k $x \leq 2MN$ the total length of ing $x \leq 2MN$ xing $x \leq 2MN$</td><td>aness e length els: agth A A T each chip</td><td>1.5</td></t<> | z: Chip thick ness a: LCD sid ack between pane in x: Chip len ing $x \leq 2MN$ /3k $x \leq 2MN$ the total length of ing $x \leq 2MN$ xing $x \leq 2MN$ | aness e length els: agth A A T each chip | 1.5 |



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| NO. | ltem | Criterion | AQL |
|-----|--|---|-----|
| | | Symbols: x: Chip length y: Chip width z: Chip thickness k: Seal width t: Glass thickness a: LCD side length L: Electrode pad length 7.2 Protrusion over terminal: 7.2.1 Chip on electrode pad: | |
| | | y: Chip width x: Chip z: Chip length thickness | |
| | | $y \le 0.5 mm$ $x \le 2 MM$ $0 < z \le t$ | |
| | | 7.2.2 Non-conductive portion: | |
| 07 | Glass crack | y z z y z z z x | 1.5 |
| | | y: Chip width length thickness | |
| | | $y \le L \qquad x \le 2MM \qquad 0 < z \le t$ | |
| | If there chipped area touches the ITO terminal, over 2/3 of the ITO must remain and be inspected according to electrode terminal specifications. If the product will be heat sealed by the customer, the alignment mark must mot be damaged. 7.2.3 Substrate protuberance and internal crack | | |
| | | y≤1/3L X≤2MM | |



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| NO. | ltem | Criterion | AQL |
|-----|-----------------------|--|--|
| 08 | Cracked glass | No crack is allowed. | 1.5 |
| 09 | Backlight elements | 9.1 Illumination source flickers when lit. 9.2 Spots or scratches that appear when lit must be judged. Using LCD spot, lines and contamination standards. 9.3 Backlight doesn't light or color is wrong. | 1.5 1.5 0.65 |
| 10 | Bezel | No scratches with W>0.1 and Length>2.5mm. | 1.5 |
| 11 | PCB、COB | 11.1 COB seal may not have pinholes larger than 0.2mm or contamination. 11.2 COB seal surface may not have pinholes through to the IC. 11.3 The height of the COB should not exceed the height indicated in the assembly diagram. 11.4 There may not be more than 2mm of sealant outside the seal area on PCB. And there should be no more than three places. 11.5 Parts on PCB must be the same as on the production characteristic chart, There should be no wrong parts, missing parts or excess parts. 11.6 The jumper on the PCB should conform to the product characteristic chart. | 1.5 1.5 1.5 1.5 0.65 0.65 |
| 12 | FPC | FPC damage per IPC guidelines.(IPC-A-610) Nicks or damage along the edges of the flexible printed cir-cuitry and cutouts,providing the penetration does not exceed 50% of the distance from the edge to the nearest conductor to 2.5mm[0.1in], Whichever is less. | 1.5 |
| 13 | Soldering | 13.1 No cold solder joints, missing solder connections, oxidation or icicle. 13.2 No short circuits in components on PCB or FPC. 13.3 Soldering per IPC guidelines.(IPC-A-610) | 1.5 0.65 |



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| | | Onteriori | | | AQL |
|---------------------------------|--|---|---|--|---|
| Touch Panel Chipped glass | Symbols: x: Chip length y: C k: Seal width t: To L: Electrode pad le 14.1 General glass 14.1.1 Chip on par I = I = I = I = I = I = I = I = I = I = | hip width buch Panel Total thickr angth s chip: nel surface and crack to y: Chip width ≦ 1/2 k and not over viewing area more chips, x is the to k: | z: Chip thickness a: LCD side I between panels: x: Chip length $x \le 2MM$ | ness length | 2.5 |
| | $z: Chip thickness$ $z \le t$ $O Unit: mm O If there are 2 or$ | y: Chip width ≦1/2 k and not over viewing area more chips, x is the to | x: Chip length x≦2MM tal length of each | chip | |
| | Touch Panel Chipped glass | x: Chip length y: C k: Seal width t: To L: Electrode pad le 14.1 General glass 14.1.1 Chip on parImage: Touch Panel Chipped glass $z: ChipthicknessChippedglass\odot Unit: mm\odot If there are 2 or14.1.2 Corner craceImage: Touch PanelChippedglass\odot Unit: mm\odot If there are 2 or14.1.2 Corner craceImage: Touch PanelChippedglass\Box Unit: mm\odot If there are 2 or14.1.2 Corner craceImage: Touch PanelChippedglassImage: Touch Panel\odot Unit: mm\odot If there are 2 or14.1.2 Corner craceImage: Touch PanelChippedglassImage: Touch Panel\odot Unit: mm\odot If there are 2 or14.1.2 Corner crace$ | x: Chip length y: Chip width k: Seal width t: Touch Panel Total thickr L: Electrode pad length 14.1 General glass chip: 14.1.1 Chip on panel surface and crack tr14.1.1 Chip on panel surface and crack tr14.1.2 Chip thickness17 Unit: mm \odot If there are 2 or more chips, x is the to14.1.2 Corner crack:14.1.2 Corner c | X: Chip length y: Chip widthZ: Chip thick k: Seal width t: Touch Panel Total thickness a: LCD side L: Electrode pad length 14.1 General glass chip: 14.1.1 Chip on panel surface and crack between panels:Image: the state of the state | x: Chip length y: Chip widthz: Chip thickness k: Seal widthz: Chip thickness a: LCD side length L: Electrode pad length 14.1 General glass chip: 14.1.1 Chip on panel surface and crack between panels:14.1.1 Chip on panel surface and crack between panels:14.1.2 Chip widthx: Chip thicknessy: Chip widthx: Chip thicknessy: Chip widthx: Chip there are 2 or more chips, x is the total length of each chip 14.1.2 Corner crack:14.1.2 Corner crack:14.1.2 Corner crack:14.1.2 Corner crack:14.1.2 Corner crack:15.1 Chip thickness16.1 Chip thickness17.2 Chip width17.2 Chip thickness18.3 Chip thickness19.4 Chip thickness19.4 Chip thickness19.5 Chip width19.5 Chip thickness19.6 Chip thickness19.6 Chip thickness19.6 Chip there are 2 or more chips, x is the total length of each chip10.6 Chip there are 2 or more chips, x is the total length of each chip10.6 Chip there are 2 or more chips, x is the total length of each chip |



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| NO. | Item | Criterion | | AQL |
|-----|--|---|--|------------------------------|
| 15 | Touch Panel(Fish eye、 dent and bubble on film) | SIZE(mm)Acceptable Q'ty $\Phi \leq 0.2$ Accept no dense $0.2 < D \leq 0.4$ 5 $0.4 < D \leq 0.5$ 2 $0.5 < D$ 0 | | 1.5 |
| 16 | Touch Panel Newton ring | Newton ring dimension $\leq 1/2$ touch panel area and not affect font and line distortion($\leq 2.5\%$), it is acceptable. | | |
| 17 | Touch Panel Linearity | Less than 2.5% is acceptable. | | 1.5 |
| 18 | LCD Ripple | Touch the touch panel , can not see the LCD ripple. Pen: R 1.0mm silicon rubber. Operation Force: 80g | | |
| 19 | General appearance | 19.1 Pin type must match type in specification sheet. 19.2 LCD pin loose or missing pins. 19.3 Product packaging must the same as specified on packaging specification sheet. 19.4 Product dimension and structure must conform to product specification sheet. 19.5 product packaging shall be by trays sized to protect tft and fpc cable, 19.6 cable shall not be bent during transportation. 19.7 ton tray must be empty. | | 0.65 0.65 0.65 0.65 |



12. Handling Precautions

12.1 Mounting method

The LCD panel of AMSON TFT module consists of two thin glass plates with polarizes which easily be damaged. And since the module in so constructed as to be fixed by utilizing fitting holes in the printed circuit board.

Extreme care should be needed when handling the LCD modules.

12.2 Caution of LCD handling and cleaning

When cleaning the display surface, Use soft cloth with solvent

[Recommended below] and wipe lightly

- Isopropyl alcohol
- Ethyl alcohol

Do not wipe the display surface with dry or hard materials that will damage the polarizer surface.

Do not use the following solvent:

- Water
- Aromatics

Do not wipe ITO pad area with the dry or hard materials that will damage the ITO patterns Do not use the following solvent on the pad or prevent it from being contaminated:

- Soldering flux
- Chlorine (Cl), Sulfur (S)

If goods were sent without being sili8con coated on the pad, ITO patterns could be damaged due to the corrosion as time goes on.

If ITO corrosion happen by miss-handling or using some materials such as Chlorine (CI), Sulfur (S) from customer, Responsibility is on customer.

12.3 Caution against static charge

The LCD module use C-MOS LSI drivers, so we recommended that you:

Connect any unused input terminal to VDD or GND, do not input any signals before power is turned on, and ground your body, work/assembly areas, and assembly equipment to protect against static electricity.

12.4 packing

- Module employs LCD elements and must be treated as such.
- Avoid intense shock and falls from a height.
- To prevent modules from degradation, do not operate or store them exposed direct to sunshine or high temperature/humidity

12.5 Caution for operation

- It is an indispensable condition to drive LCD's within the specified voltage limit since the higher voltage then the limit cause the shorter LCD life.
- An electrochemical reaction due to direct current causes LCD's undesirable deterioration, so that the use of direct current drive should be avoided.
- Response time will be extremely delayed at lower temperature then the operating temperature range and on the other hand at higher temperature LCD's how dark color in them. However those phenomena do not mean malfunction or out of order with LCD's, which will come back in the specified operation temperature.
- If the display area is pushed hard during operation, some font will be abnormally displayed but it resumes normal condition after turning off once.
- Slight dew depositing on terminals is a cause for electro-chemical reaction resulting in terminal open circuit.

Usage under the maximum operating temperature, 50%Rh or less is required.



12.6 storing

In the case of storing for a long period of time for instance, for years for the purpose or replacement use, the following ways are recommended.

- Storage in a polyethylene bag with the opening sealed so as not to enter fresh air outside in it. And with no desiccant.
- Placing in a dark place where neither exposure to direct sunlight nor light's keeping the storage temperature range.
- Storing with no touch on polarizer surface by the anything else.
 [It is recommended to store them as they have been contained in the inner container at the time of delivery from us.

12.7 Safety

- It is recommendable to crash damaged or unnecessary LCD's into pieces and wash off liquid crystal by either of solvents such as acetone and ethanol, which should be burned up later.
- When any liquid leaked out of a damaged glass cell comes in contact with your hands, please wash it off well with soap and water.

13. Precaution for Use

13.1

A limit sample should be provided by the both parties on an occasion when the both parties agreed its necessity. Judgment by a limit sample shall take effect after the limit sample has been established and confirmed by the both parties.

13.2

On the following occasions, the handing of problem should be decided through discussion and agreement between responsible of the both parties.

- When a question is arisen in this specification.
- When a new problem is arisen this is not specified in this specification.
- When an inspection specifications change or operating condition change in customer is reported to AMSON TFT and some problem is arisen in this specification due to the change.
- When a new problem is arisen at the customer's operating set for sample evaluation in the customer site.

14. Packing Method

| No. | ltem | Dimensions(mm) | Quantity | Remark |
|-----|---------------|---|----------|--------|
| 1 | LCM Module | 64.00*85.00*4.2 | 162PCS | |
| 2 | TRAY | 385*340*21 (include 9pcs products/one tray) | 9PCS | |
| 3 | SMALL CARTON | 392*345*115 (include 81pcs products/one carton) | 2PCS | |
| 4 | LARGE CARTON | 405*355*260 (include 162pcs products/one carton) | 1PCS | |